



2014 IEEE



Compound Semiconductor IC Symposium



INTEGRATED CIRCUITS and DEVICES in
GaAs, InP, GaN, SiGe, and other compound semiconductor and CMOS technologies



October 19–22, 2014

Hyatt Regency La Jolla at Aventine, San Diego, California, USA



Sponsored by the IEEE Electron Devices Society
Technically co-sponsored by the Solid State Circuits Society
and the Microwave Theory & Techniques Society



FINAL CALL FOR PAPERS

2014 CSIC Symposium

Starting in 1978 as the GaAs IC symposium, CSICS has evolved to become the preeminent international forum for developments in compound semiconductor integrated circuits, embracing GaAs, InP, GaN, SiGe, as well as nanoscale CMOS technology. Coverage includes all aspects of the technology from materials issues, device fabrication and modeling through IC design and testing, high volume manufacturing, and system applications. Specific technical areas of interest include:

- Innovative device concepts in emerging technologies
 - GaN, InP, III-V on Si, Ge on Si, Graphene
- Analog, RF, mixed-signal, mm-wave, THz circuit blocks and ICs in III-V, CMOS, and SiGe BiCMOS
- Power conversion circuits and technologies
- Optoelectronic and photonic devices and OEICs
- System applications
 - Wireless handsets and base stations
 - Vehicular and military RADAR
 - High-speed digital systems
 - Fiber optics and photonics
- Device and circuit modeling / EM and EDA tools
- Thermal simulation and advanced packaging of high-power devices and ICs
- Device and IC manufacturing processes, testing methodologies, and reliability

Symposium Highlights

High quality technical papers will be selected from submissions for oral presentation and publication in the Symposium Digest. Invited papers and panel sessions will complete the program. Extended versions from the Symposium will be published in a special issue of the *IEEE Journal of Solid State Circuits*.

Student Paper Competition

For the very first time, CSICS will include a Student Paper Competition. All students registered full-time during the time that their submitted work was performed are eligible to participate. A confirmed finalist will be announced at CSICS in October and receive special recognition. Competition rules and requirements will be posted on the Symposium website.

Primer Course

On Sunday evening, Professor Waleed Khalil of Ohio State will teach an expanded primer course on Si RFIC design. The course is intended for participants of all technical backgrounds who wish to learn or refresh their understanding of the fundamentals of designing the principal circuit building blocks in radio and radar SOCs. Among the blocks covered are PAs, LNAs, Mixers, VCOs, PAs, as well as integrated passives, with examples drawn from both CMOS and SiGe technology. The primer is an excellent way to start the symposium and is guaranteed to enhance attendee appreciation of the technical program.

Short Courses

On Sunday, CSICS is proud to present two short courses: “GaN HEMT Device Modeling” and “Fundamentals of Power Conversion and Envelope Tracking.” Taught by leading experts, they are intended for both technologists and IC designers who seek a comprehensive understanding of the latest trends and techniques in GaN technology and circuit design. Organizer: Harris Moyer, HRL Laboratories, Ph: +1-310-317-5784, E-mail: hpmoyer@hrl.com.

Deadline for Electronic Receipt of Papers is Close of Business, May 2, 2014

Authors must submit a paper (not more than 4 pages including figures and other supporting material) of results not previously published or not already accepted by another conference. Papers will be selected on the basis of the content and measured results.

The abstract must concisely and clearly state:

- a) The purpose of the work
- b) What specific new results have been obtained
- c) How it advances the state-of-the-art or the industry
- d) References to prior work
- e) Sub-committee preference:
 - Advanced Devices and Modeling
 - Analog, RF, and Microwave ICs
 - mm-Wave and THz ICs
 - High-Speed digital, Mixed-Signal & Optoelectronic ICs

The paper must include: the title, name(s) of the author(s), organization(s) represented, corresponding authors' postal and electronic addresses, and telephone number. A paper template is available from www.csics.org. Please indicate your preference for subcommittee review. The program committee will honor the authors' preference where possible, but reserves the right to place the paper in other review categories.

All company and governmental clearances must be obtained prior to submission of the paper.

Authors must submit their papers in PDF format electronically using the www.csics.org web page. They will be informed regarding the results of their submissions by June 13, 2014. Authors of accepted papers will be required to submit to the IEEE their final camera-ready paper by July 25, 2014 for publication in the Symposium Technical Digest. The accepted papers may be used for publicity purposes. Portions of these papers may be quoted in magazine articles publicizing the Symposium. **Please note on the paper if this is not acceptable.**

Further questions on paper submission may be addressed to the Symposium Technical Program Chair:

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All Symposium information, including paper submission instructions and a link to our paper submission address is available on the CSICS website at:

www.csics.org

2014 Compound Semiconductor IC Symposium Exhibition

As in past years, the Symposium will sponsor an exhibition of products from various vendors of materials, IC products, processing equipment, test equipment, CAD tools, and foundry services specifically addressing the Compound Semiconductor industry. Numerous vendors will be on-hand to discuss their products and to answer questions.

Inquiries concerning the exhibits should be addressed to:

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The following members of the Technical Program Committee are available for guidance or for answering questions regarding paper preparation:

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